GNP1150TCA-Z

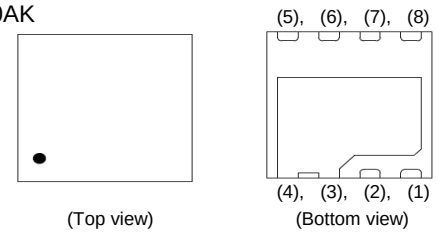
GaN Enhancement Mode Power Transistor

Datasheet

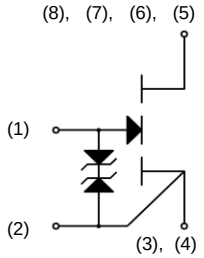
V_{DSS}	650V
$R_{DS(on)}$ (Typ.)	150mΩ
$Q_{G,\ typ.}$	2.7nC
$I_{D(Tc=25°C)}$ *1	11A
Q_{oss} @ 400V	18.5nC
Q_{rr}	0nC

●Outline

DFN8080AK



●Inner circuit



(1) Gate
(2) Kelvin Source
(3) Source
(4) Source
(5) Drain
(6) Drain
(7) Drain
(8) Drain

●Features

- 650V E-mode GaN FET
- 150mΩ Resistance
- 2.7nC Gate Charge

●Application

- High switching frequency converter
- High density converter

●Packaging specifications

Type	Packing	Embossed tape
	Reel size (mm)	330
	Tape width (mm)	16
	Basic ordering unit (pcs)	3500
	Taping code	E2
	Marking	GNP1150TCA

●Absolute maximum ratings (T_a = 25°C)

Parameter		Symbol	Value	Unit
Continuous Drain current	T_c = 25°C	I_D *1	11	A
	T_c = 125°C		5	A
Pulse Drain current	T_c = 25°C	$I_{D,pulse}$ *1*2	35	A
	T_c = 125°C		17	A
Drain - Source Voltage		V_{DSS}	650	V
Transient Drain - Source Voltage		$V_{DSS(transient)}$ *3	750	V
Gate - Source voltage (DC)		V_{GSS}	-10 to +6	V
Transient Gate - Source voltage		$V_{GSS(transient)}$ *4	8.5	V
Power dissipation(Tc=25°C)		P_{tot}	46.3	W
Junction temperature		T_j	150	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V T_j = 25°C	650	-	-	V
Zero Gate voltage Drain current	I_{DSS}	V_{GS} = 0V, V_{DS}=650V T_j = 25°C T_j = 150°C	- -	1 90	100 -	μA
Gate - Source leakage current	I_{GSS+}	V_{GS} = 6.0V, VDS = 0V	-	0.1	3	mA
Gate threshold voltage	$V_{GS\ (th)}$	V_{DS} = 50mV, I_D = 18mA	1	1.45	2.4	V
Static Drain - Source on - state resistance	$R_{DS(on)}$ *5	V_{GS} = 5.0V, I_D = 1.9A T_j = 25°C T_j = 150°C	- -	155 388	202 -	mΩ
		V_{GS} = 5.5V, I_D = 1.9A T_j = 25°C T_j = 150°C	- -	150 375	195 -	mΩ
Gate input resistance	R_G	f = 100MHz, open drain	-	2.6	-	Ω

●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - ambient	R_{thJA}	-	46.5	-	°C/W
Thermal resistance, junction - case	R_{thJC}	-	2.7	-	°C/W
Reflow soldering temperature	T_{solder} *6	-	-	260	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	V_{GS} = 0V V_{DS} = 400V f = 1MHz	-	112	-	pF
Output capacitance	C_{oss}		-	19	-	
Reverse transfer capacitance	C_{rss}		-	0.3	-	
Effective output capacitance, energy related	$C_{o(er)}$	V_{GS} = 0V V_{DS} = 0V to 400V	-	29	-	pF
Effective output capacitance, time related	$C_{o(tr)}$	V_{GS} = 0V V_{DS} = 0V to 400V	-	47	-	pF
Output charge	Q_{oss}	V_{GS} = 0V V_{DS} = 0V to 400V	-	18.5	-	nC
Total Gate charge	Q_g *7	V_{DS} = 400V I_D = 5A V_{GS} = 6V/0V	-	2.7	-	nC
Gate - Source charge	Q_{gs} *7		-	0.3	-	
Gate - Drain charge	Q_{gd} *7		-	1.1	-	
Gate plateau voltage	V_{plat} *7		-	2.4	-	V
Turn - on delay time	$t_{d(on)}$ *7	V_{DS} = 400V I_D = 5A V_{GS} = 6V/0V R_G = 10Ω	-	4.7	-	ns
Rise time	t_r *7		-	5.3	-	
Turn - off delay time	$t_{d(off)}$ *7		-	6.2	-	
Fall time	t_f *7		-	8.3	-	

●Reverse conduction electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Source-Drain reverse voltage	V_{SD}	V_{GS} = 0V, I_{SD}=1.9A	-	2.3	-	V
Reverse recovery time	t_{rr} *7		-	0	-	ns
Reverse recovery charge	Q_{rr} *7		-	0	-	nC
Peak reverse recovery current	I_{rrm} *7		-	0	-	A

*1 Limited and calculated by maximum temperature allowed..

*2 V_{GS}=6V,Duty=0.1, t_{pulse}=1μs.

*3 t_{pulse}=1μs, <10 hrs of total time.

*4 $t_{pulse<}$20ns, <0.5 hr of total time.

*5 Maximum Id applied at Final Test is 1.9A.

*6 MSL 3.

*7 Pulsed.

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

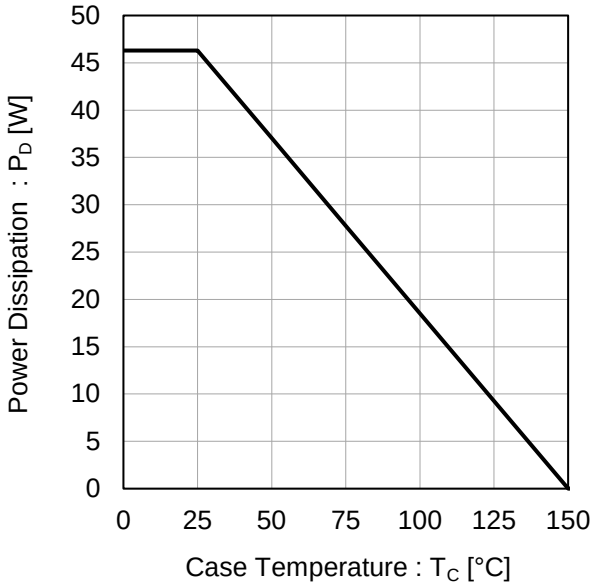


Fig.2 Normalized Transient Thermal Resistance vs. Pulse Width

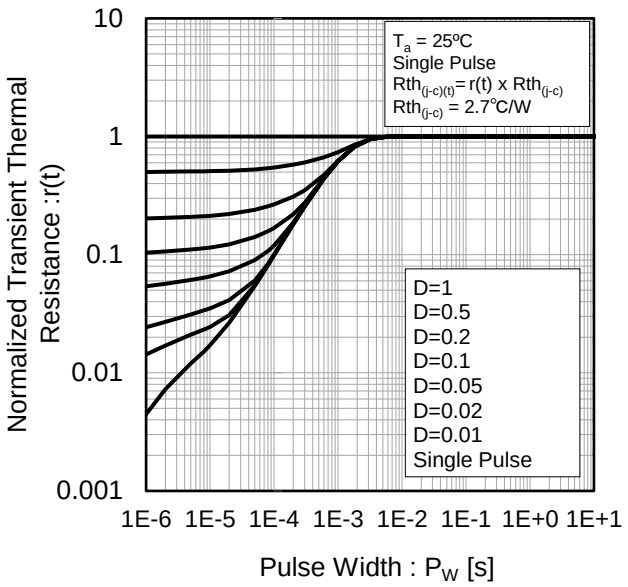


Fig.3 Maximum Safe Operating Area(Ta=25°C)

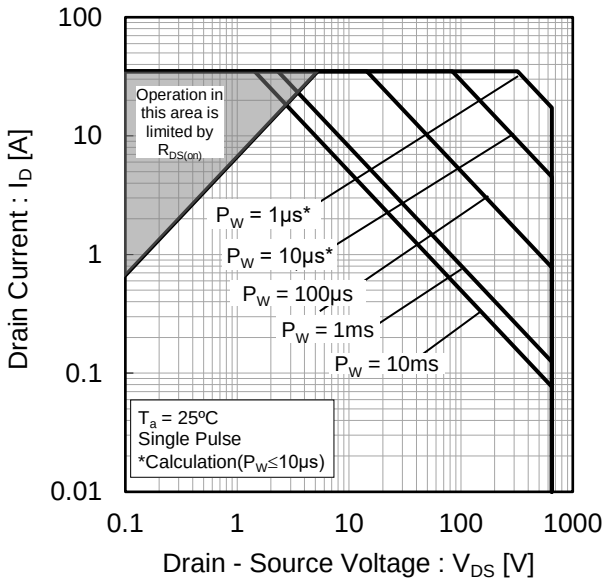
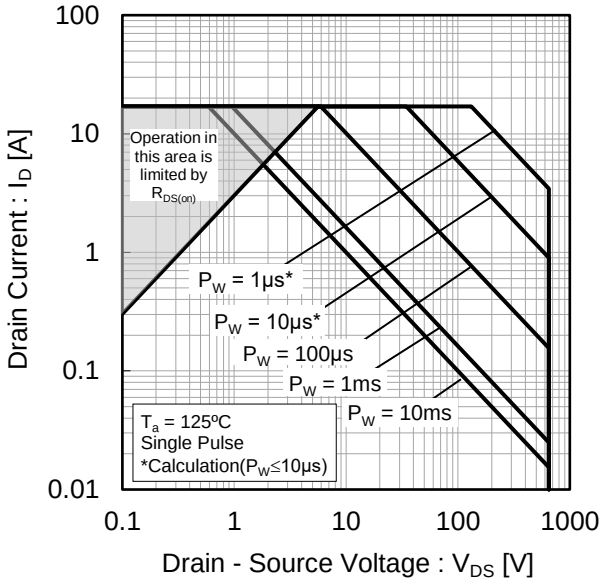


Fig.4 Maximum Safe Operating Area(T_a=125°C)



●Electrical characteristic curves

Fig.5 T_j = 25ºC Typical Output Characteristics

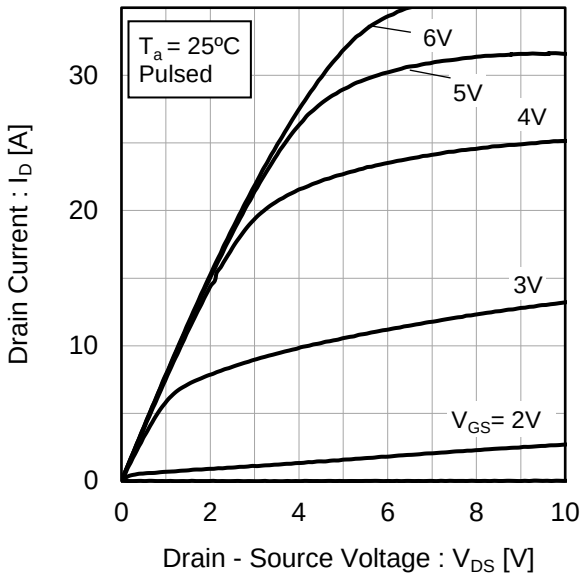


Fig.6 T_j = 125ºC Typical Output Characteristics

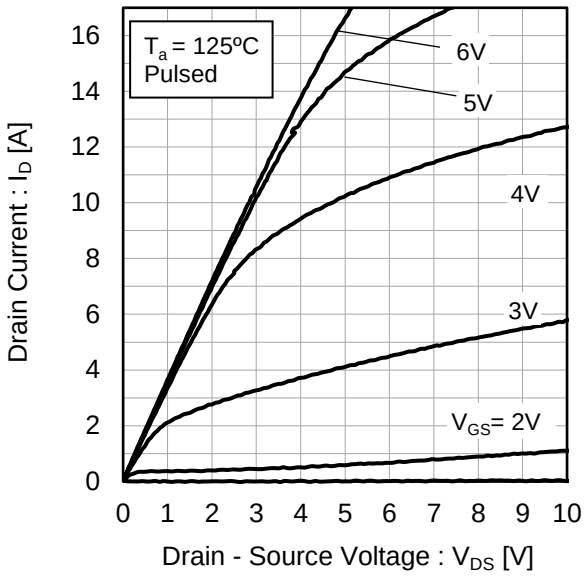


Fig.7 Typical Transfer Characteristics

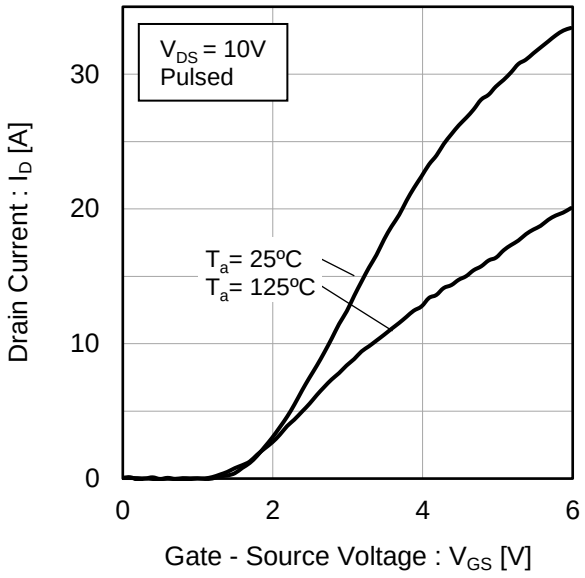
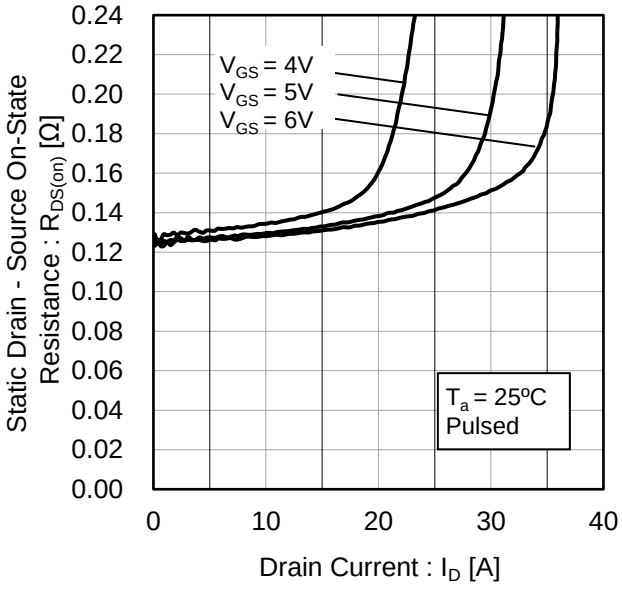


Fig.8 Static Drain - Source On - State Resistance vs. Drain - Source Current



●Electrical characteristic curves

Fig.9 T_j = 25ºC 3rd Quadrant Characteristics

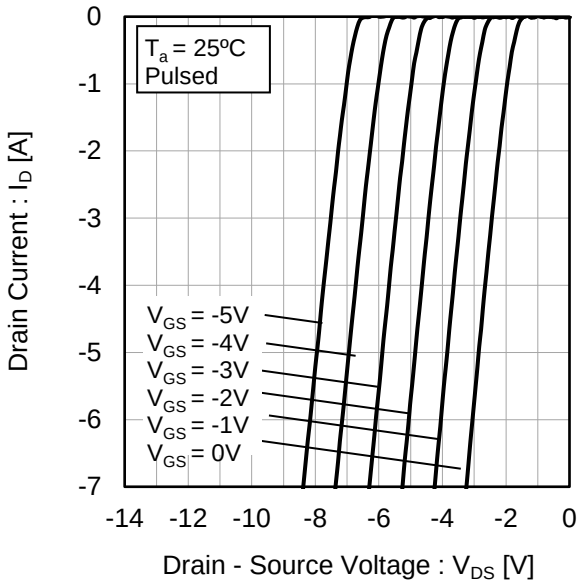


Fig.10 T_j = 125ºC 3rd Quadrant Characteristics

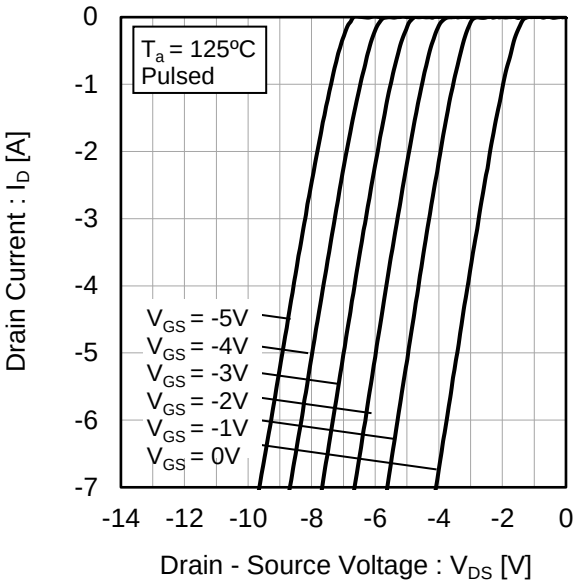


Fig.11 Typical Capacitance vs. Drain - Source Voltage

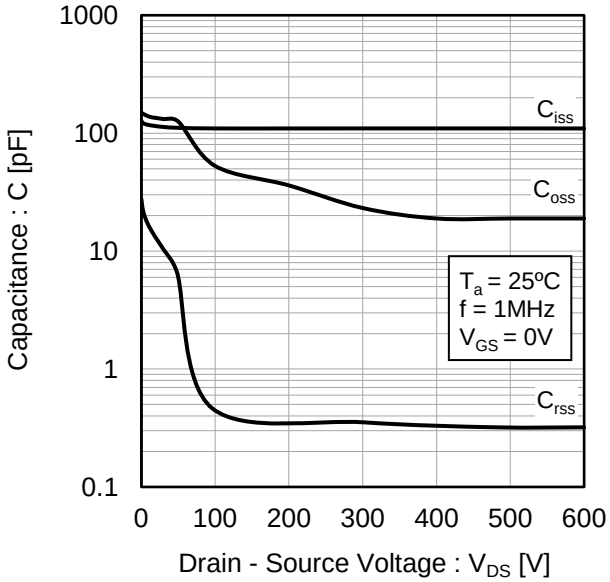
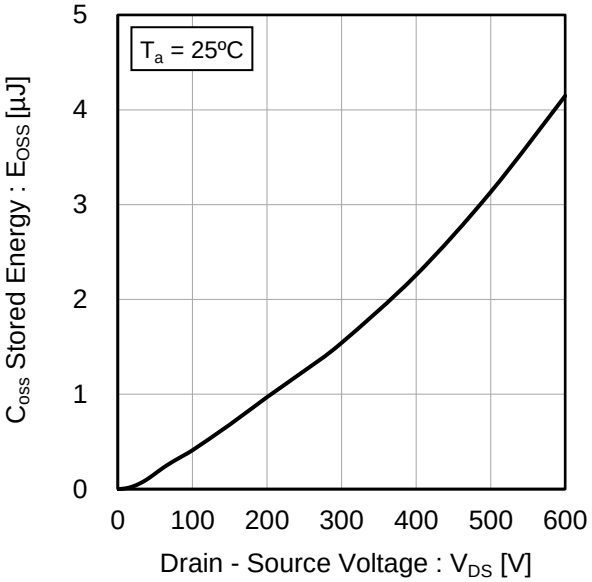
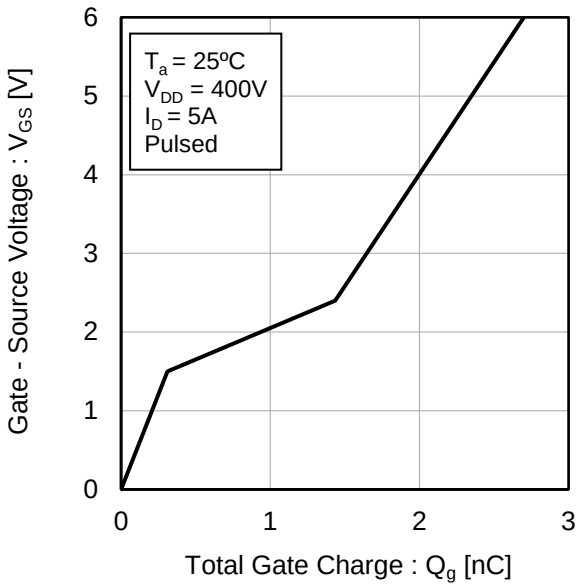


Fig.12 C_{oss} Stored Energy

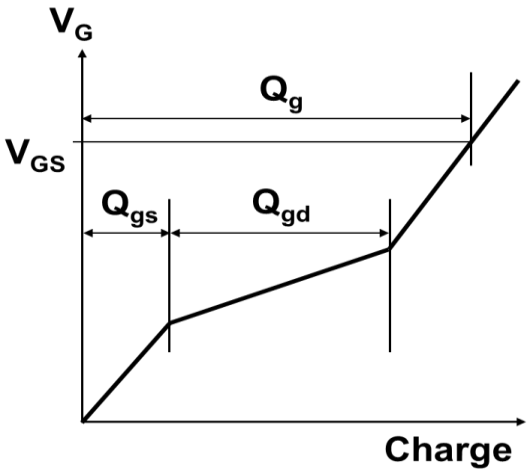


●Electrical characteristic curves

Fig.13 Dynamic Input Characteristics



*Gate Charge Waveform



●Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

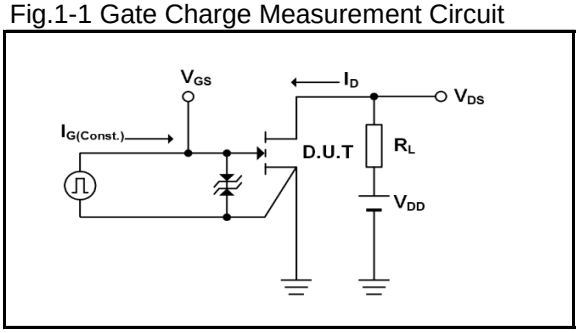


Fig.2-1 Switching Characteristics Measurement Circuit

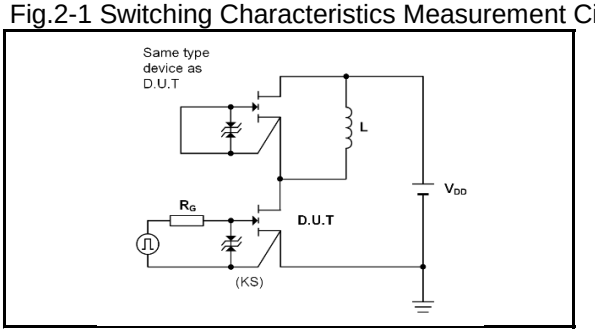


Fig.2-2 Waveforms for Switching Time

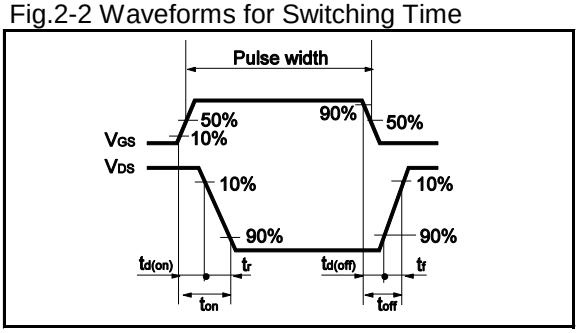
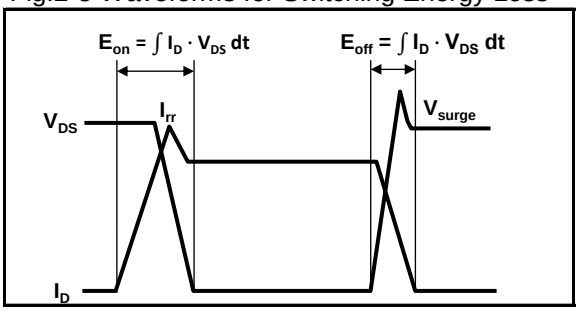


Fig.2-3 Waveforms for Switching Energy Loss



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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

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   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.) ; or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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